MITSUI
KINZOKU

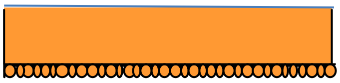
TQ-M4-VSP

- 於平滑面實施超細微處理之極低粗度電解銅箔（VSP箔）
  Very smooth profile ED copper foil (VSP) with very low profile surface treatment.
- 銅箔於全面蝕刻後，於PI具良好的透視度。
  Very good performance for transparency and visibility of PI after etching copper foil.
- 超低粗糙度處理面，非常適合於高頻高速的應用。
  Possible to use high frequency application due to very low prfile.

用途/Application

**・軟性電路板
/Flexible Print Board**

構成/Composition



生產地點/Production Site

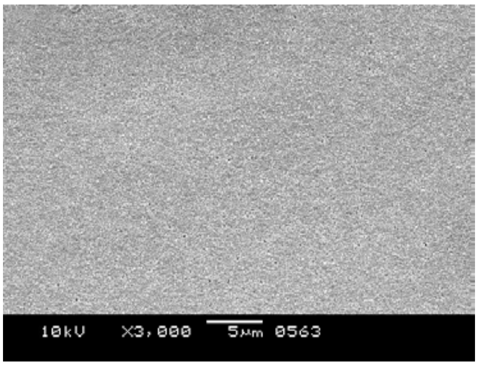
・日本/Japan

代表性特性數據/Representive

	μm	Area weight (g/m2)	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
TQ-M4-VSP	12	100	0.6	340	9	0.6
	18	148	0.6	340	12	0.7

※上述表列為代表性數據非保証值
This is representative data, not guaranteed.

處理面/Laminate side



阻劑面/ resist side